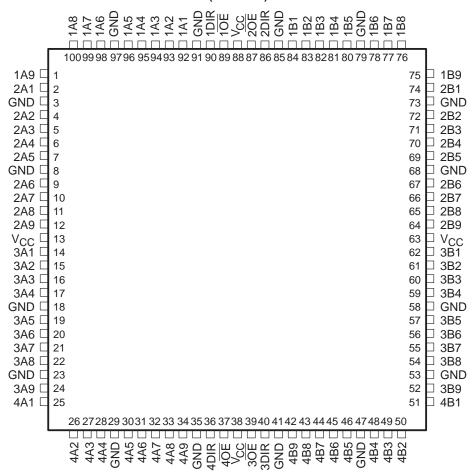
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- Members of the Texas Instruments
  Widebus+™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  < 0.8 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Impedance State During Power Up and Power Down
- Released as DSCC SMD 5962-9557701NXD
- PZ Package Qualified for Military Per MIL-PRF-38535 (QML)

- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 100-Pin Plastic Thin Quad Flat (PZ) Package With 14 × 14-mm Body Using 0.5-mm Lead Pitch and Space-Saving 100-Pin Ceramic Quad Flat (HS) Package<sup>†</sup>

### 'ABTH32245 . . . PZ PACKAGE (TOP VIEW)



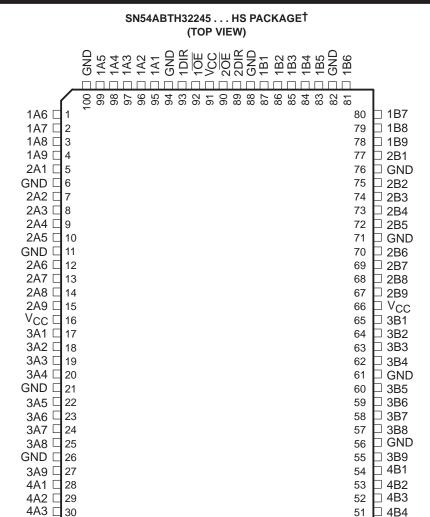
† The HS package is not production released.



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† For HS package availability, please contact the factory or your local TI Field Sales Office.

GND | 32 4A5 | 33 4A6 | 34 4A7 | 35 4A8 | 36 4A9 | 37 GND | 38 4DIR | 39 4DIR | 39 4DIR | 40 VCC | 41 4DIR | 42 4DIR | 44 4B9 | 45 4B8 | 46 4

### description

The 'ABTH32245 are 36-bit (quad 9-bit) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as four 9-bit transceivers, two18-bit transceivers, or one 36-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) inputs. The output-enable  $(\overline{OE})$  inputs can be used to disable the device so that the buses are effectively isolated.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.



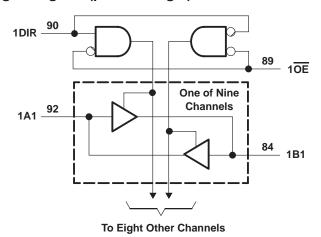
### description (continued)

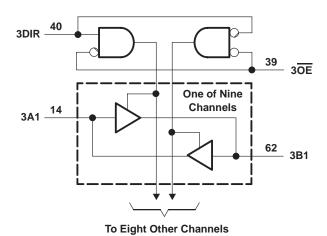
The SN54ABTH32245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32245 is characterized for operation from –40°C to 85°C.

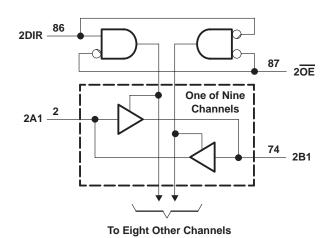
FUNCTION TABLE (each 9-bit section)

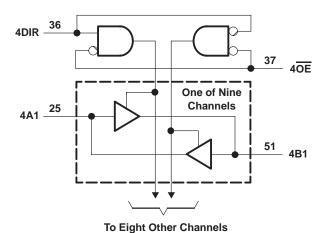
INP	UTS	ODEDATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

### logic diagram (positive logic)









Pin numbers shown are for the PZ package.

### SN54ABTH32245, SN74ABTH32245 **36-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS**

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	$-0.5 \text{ V to 7 V}$
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	. $-0.5\ V$ to 5.5 $V$
Current into any output in the low state, IO: SN54ABTH32245	96 mA
SN74ABTH32245	128 mA
Input clamp current, $I_{ K }(V_{ I } < 0)$	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): PZ package	50°C/W
Storage temperature range, T <sub>stq</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

				132245	SN74ABTH32245		UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	Vcc	0	VCC	V	
loн	OH High-level output current					-32	mA
l <sub>OL</sub>	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	CC Power-up ramp rate			·	200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			SN54ABTH32245			ABTH32	2245	UNIT	
PAI	RAMETER	I IEST CONI	DITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP†	MAX	UNII	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 4.5 V,$	$I_{OH} = -3 \text{ mA}$	2.5			2.5				
\/~		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3			V	
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2						٧	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$				2				
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55			0.55	V	
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA						0.55	V	
V <sub>hys</sub>					100			100		mV	
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND						±1		
١.	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND						±20	μΑ	
l tı	Control inputs	V <sub>CC</sub> = 5.5 V,	VI = VCC or GND			±1				μА	
	A or B ports	VCC = 5.5 V,	AI = ACC OLGIND			±20				μΑ	
ha in	hold) A or B ports	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0.8 V	100			100			μА	
l(hold)	A of B ports	VCC = 4.5 V	V <sub>I</sub> = 2 V	-100			-100				
lozpu <sup>‡</sup>	‡	$V_{CC} = 0$ to 2.1 V, $V_{O} = 0.5$	V to 2.7 V, $\overline{OE} = X$			±50			±50	μΑ	
lozpd <sup>‡</sup>	‡	$V_{CC} = 2.1 \text{ V to } 0, V_{O} = 0.5$	V to 2.7 V, $\overline{OE} = X$			±50			±50	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$						±100	μΑ	
ICEX		$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50			50	μΑ	
ΙΟ§		$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-100	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high			3			3		
ICC		$I_{O} = 0$ ,	Outputs low			20			20	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2			2		
$\Delta I_{CC}$ V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1			1	mA			
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3.5			3.5		pF	
C <sub>io</sub>	A or B ports	A or B ports $V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			9.5			9.5		pF	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C#			SN54ABTH32245		SN74ABTH32245		UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1.7	3.2	4.4	1	5.3	1.7	5	
t <sub>PHL</sub>	AUD	BULA	1.7	3.3	4.6	1	5.3	1.7	5.2	ns
<sup>t</sup> PZH	<del></del>	B or A	1.6	4.2	6.1	1	7.6	1.6	7.3	no
t <sub>PZL</sub>	ŌĒ	BULA	2.7	5.2	7	1.5	8.2	2.7	8.1	ns
t <sub>PHZ</sub>	ŌĒ	B or A	1.3	3.9	6.1	0.8	6.7	1.3	6.5	
tPLZ	OE .	DULA	2	4.4	6.6	1	7.2	2	6.9	ns

<sup>#</sup>These limits apply only to the SN74ABTH32245



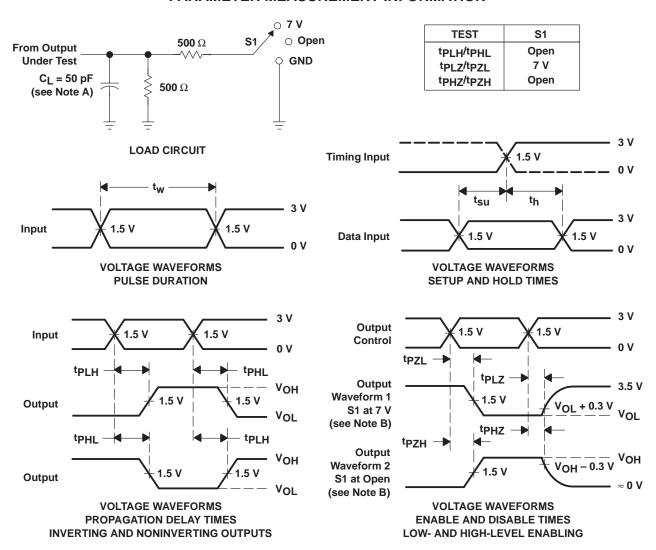
<sup>&</sup>lt;sup>‡</sup> This parameter is specified by characterization.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $<sup>\</sup>P$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







com 18-Sep-2008

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9557701NXD	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
SN74ABTH32245PZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
SN74ABTH32245PZG4	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

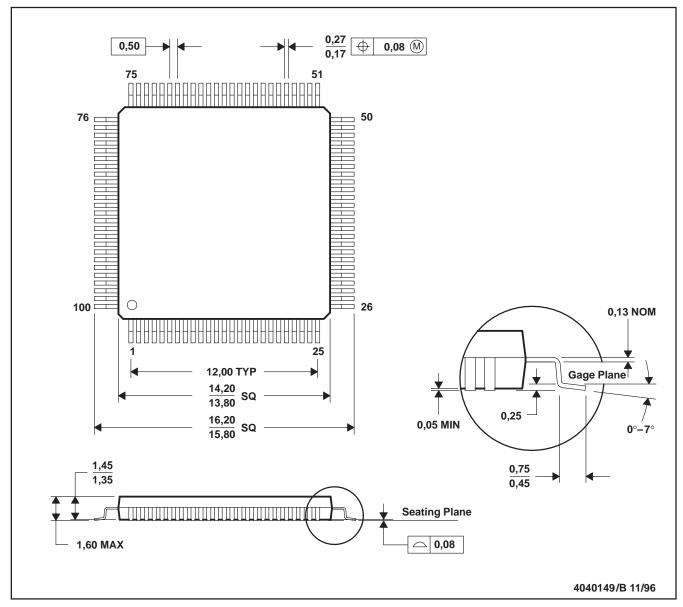
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### PZ (S-PQFP-G100)

### PLASTIC QUAD FLATPACK

1



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-026

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